



MITSUBISHI
ELECTRIC

Changes for the Better

POWER MODULES

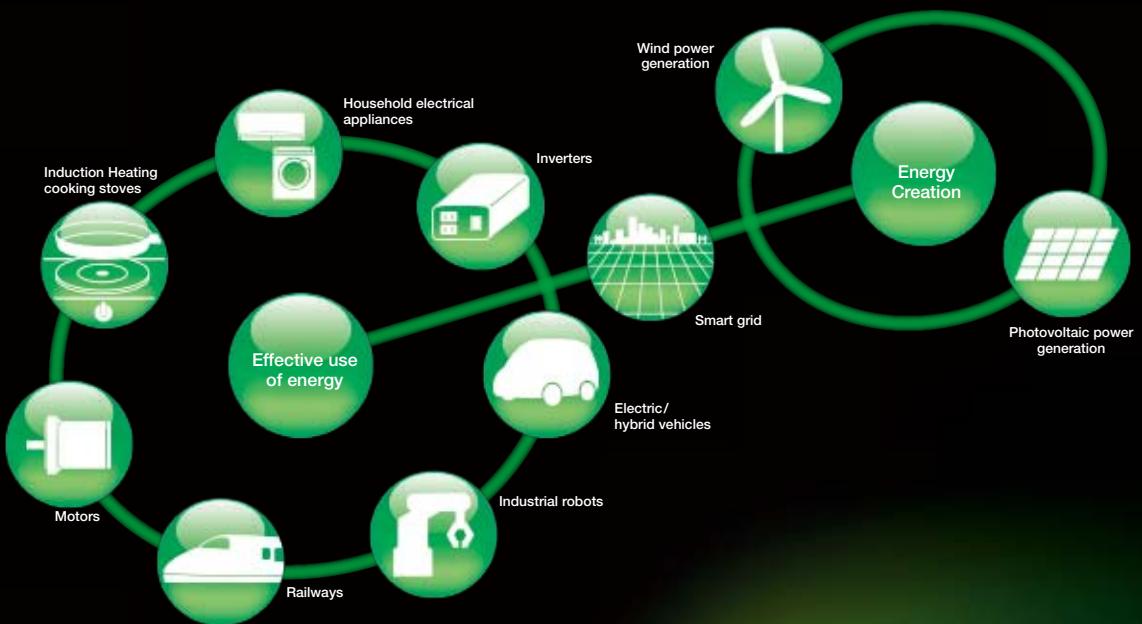
for a greener tomorrow



Power Modules

Innovative Power Devices for a Sustainable Future

Mitsubishi Electric power modules are at the forefront of the latest energy innovations that seek to solve global environmental issues while creating a more affluent and comfortable society for all. Some of these innovations are photovoltaic (PV) and wind power generation from renewable energy sources, smart grids realizing efficient supply of power, hybrid/electric vehicles (HVs/EVs) that take the next step in reducing carbon emissions and fuel consumption, and home appliances that achieve ground-breaking energy savings. Whether in appliances, railcars, EVs or industrial systems, our power modules are key elements in changing the way energy is used.





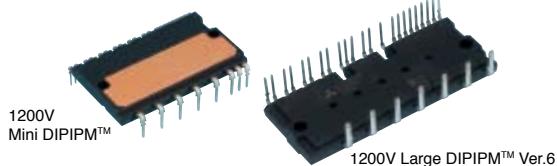
New Products

New highly efficient intelligent power modules for air conditioners and industrial applications

1,200V Large DIPIPM™ Ver.6 and 1,200V Mini DIPIPM™

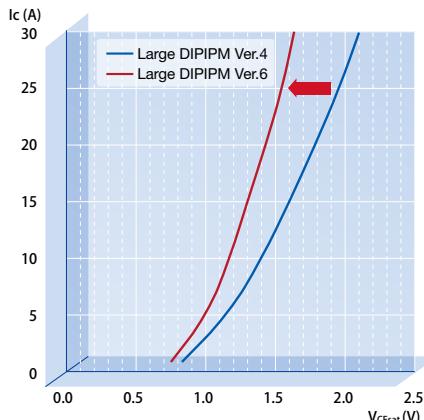
Key Features

- Reduced external components thanks to built-in bootstrap diodes (BSD) with a current limit resistor.
- Sixth-generation IGBT chips featuring the CSTBT™ structure enable power loss to be reduced by approximately 10% compared to conventional products (Large DIPIPM Ver. 4 series, 5A–35A).
- By employing a Mini DIPIPM™ package for the first time in a 1,200V product, the outline size has been reduced approximately 34% compared to conventional products (Large DIPIPM™ Ver. 4 series, 5A–35A).



CSTBT: Carrier Stored Trench-Gate Bipolar Transistor
DIPIPM: Dual-in-line Package Intelligent Power Module

■ IGBT saturation voltage characteristics
 $T_j=25^\circ\text{C}$, $V_D=15\text{V}$, typical example



Modules realizing single-control power supply and photocoupler-less systems for household appliances and low-capacity inverters

Key Features

- Transfer-molded structure with insulation sheet having high heat conductivity simultaneously provides heat dissipation and insulation
- High-voltage IC equipped with drive, protection and level-shift circuits for direct control via input signals from a CPU or microcomputer
- Compact board and highly reliable equipment realized through single power-supply and photocoupler-less systems
- Includes built-in bootstrap diode (BSD)

DIPIPM™
Dual In-Line Package
Intelligent Power Modules



Modules with built-in control and protection circuits for AC servo robots and PV power generation

Key Features

- Built-in protection circuit for short-circuiting, power supply undervoltage and overheating
- Highly compatible package with simplified printed circuit board (PCB) design
- Special intelligent power modules (IPMs) for power conditioners in PV power generation systems

IPM
Intelligent Power Modules

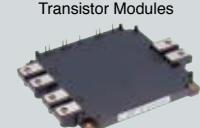


IGBT modules used in general-purpose inverters for various applications

Key Features

- Various low-inductance packages and power chips available
- Compatible with high-frequency, high-voltage (1700V) applications
- Large-capacity modules available for renewable energy systems

IGBT Modules
Insulated Gate Bipolar
Transistor Modules



Modules meeting the high voltage, current and insulation requirements of inverters for railway systems

Key Features

- High isolation package (10.2kVrms: AC60Hz 1min) matched to high catenary voltage
- Lightweight modules with aluminum silicon carbide (AlSiC) baseplate available
- Range of HV diode modules enabling highly efficient comprehensive converter design

HVIGBT Modules
High Voltage Insulated Gate Bipolar
Transistor Modules

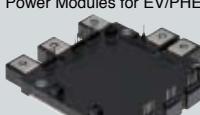


Modules realizing high performance and reliability as motor drives in HVs/EVs

Key Features

- Built-in temperature analog output function realizing highly reliable motor drive
- High-power/temperature cycle life ensures high reliability
- Compliant with the End-of-life Vehicles Directive, regulations relating to substances of environmental concern
- High traceability in managing materials/components throughout the entire production process for each product

Power Modules for Vehicles
Power Modules for EV/PHEV



Line-up of DIPIPM™

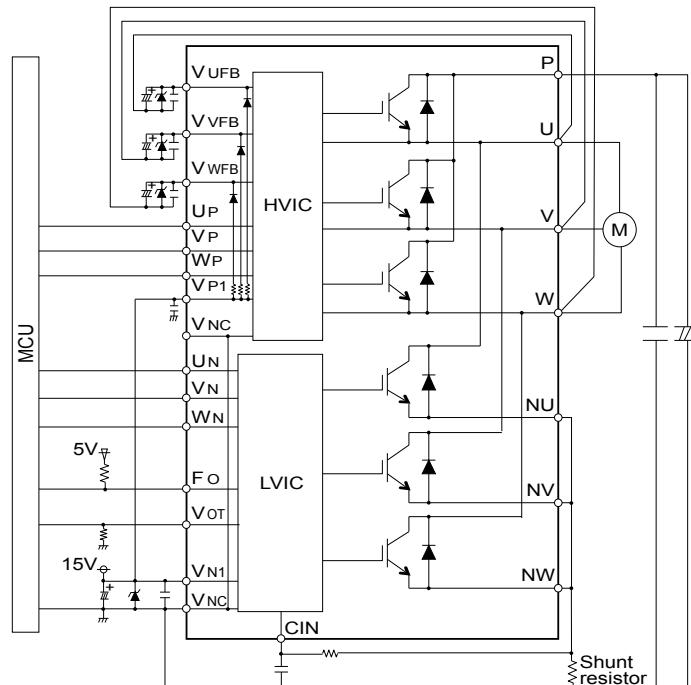
■ Series Matrix of 600V / 500V DIPIPM

V _{CES} (V)	600V						500V			
I _C (A)	Series		Ver.6	Ver.5	For Industry	Ver. 4		PFC	MOSFET	
	Super mini type	Super mini type	Super mini type	Built-in BSD	Mini Type	Large Type	Mini Type	Mini Type	Super mini type	
	Built-in BSD	Built-in BSD	Built-in BSD						Built-in BSD	
3									PSM03S93E5-A*	
5	PSS05S92F6-AG*	PS219B2-S PSS05S92E6-AG*	PS219B2-ST	PSS05S51F6* PSS05S51F6-C*					PSM05S93E5-A*	
10	PSS10S92F6-AG*	PS219B3-S PSS10S92E6-AG*	PS219B3-ST	PSS10S51F6* PSS10S51F6-C*						
15	PSS15S92F6-AG*	PS219B4-S PSS15S92E6-AG*	PS219B4-ST	PSS15S51F6* PSS15S51F6-C*				PS41764		
20	PSS20S92F6-AG*	PSS20S92E6-AG*		PSS20S51F6* PSS20S51F6-C*	PS21765		PS51787			
25										
30	PSS30S92F6-AG*	PSS30S92E6-AG*		PSS30S71F6*	PS21767-V		PS51789			
35	PSS35S92F6-AG*	PSS35S92E6-AG*								
50				PSS50S71F6*		PS21A79				
75						PS21A7A				
Chip	IGBT/MOSFET	Full-gate CSTBT	Full-gate CSTBT	CSTBT	CSTBT	Full-gate CSTBT	Trench	SJ-MOSFET	MOSFET	
HVIC	x1	x1		x3	x3	x3	-	x3	x1	
LVIC	x1	x1		x1	x1	x1	x1	x1	x1	
BSD	x3	x3		x3	x3	-	-	-	x3	
Protective Function	UV	P-side/N-side	P-side/N-side	P-side/N-side	P-side/N-side	P-side/N-side	N-side	P-side/N-side	P-side/N-side	
SC	N-side	N-side	N-side	N-side	N-side	N-side w/sense	-	N-side	N-side	
OT	N-side ^{*1}	N-side <-T>	-	-	-	-	-	-	N-side	
V _{OT} ^{*2}	N-side ^{*1}	N-side <except-T>	N-side	-	N-side	-	-	-	-	
Specification	Active Input	High (3/5V)	High (3/5V)	High (3/5V)	High (3/5V)	High (3/5V)	High (3/5V)	High (3/5V)	High (3/5V)	
Emitter pin of N-side	Open	Open	Open	Open	Open	Open	-	Open	Open	
Fault Output	N-side (UV, SC, OT)	N-side (UV, SC, OT)	N-side (UV, SC)	N-side (UV, SC)	N-side (UV, SC)	-	N-side (UV, SC)	N-side (UV, SC, OT)		
Insulation voltage	1500Vrms ^{*3}	1500Vrms ^{*3}	2500Vrms	2500Vrms	2500Vrms	2500Vrms	2500Vrms	2500Vrms	1500Vrms ^{*3}	
Insulation structure	Insulation sheet	Insulation sheet	Molding resin ^{*7} /Insulation sheet	Insulation sheet	Insulation sheet	Insulation sheet	Insulation sheet	Insulation sheet	Insulation sheet	
RoHS Directive	Compliant ^{*5}	Compliant ^{*5}	Compliant ^{*4~5}	Compliant ^{*5}	Compliant ^{*5}	Compliant ^{*6}	Compliant ^{*5}	Compliant ^{*5}	Compliant ^{*5}	
Pin Type	A: Long	A: Long	C: Control side of Zigzag None: Short	-	-	-	-	-	A: Long	

Non-Recommended : Please refrain from adopting newly.

★★: Under Development ★: New Products

■ Application circuit of Built-in BSD super mini DIPIPM™

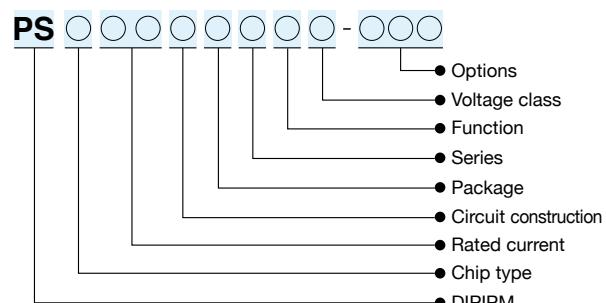


■ Series Matrix of 1200V DIPIPM

I _C (A)	Series	1200V	
		Ver.6	Ver.4
I _C (A)	Mini Type	Large Type	Large Type
3			
5	PSS05S72FT**	PSS05SA2FT**	PS22A72
10	PSS10S72FT**	PSS10SA2FT**	PS22A73
15		PSS15SA2FT**	PS22A74
25		PSS25SA2FT**	PS22A76
30			
35		PSS35SA2FT**	PS22A78-E
50		PSS50SA2FT**	PS22A79
75			
Chip	IGBT/MOSFET	CSTBT	CSTBT
	HVIC	x3	x3
	LVIC	x1	x1
	BSD	x3	x3
Protective Function	UV	P-side/N-side	P-side/N-side
	SC	N-side	N-side
	OT	-	-
	V _{OT} *2	N-side	N-side
Specification	Active Input	High(5V)	High(5V)
	Emitter pin of N-side	Open	Open
	Fault Output	N-side(UV,SC)	N-side(UV,SC)
	Insulation voltage	2500Vrms	2500Vrms
	Insulation structure	Insulation sheet	Insulation sheet
	RoHS Directive	Compliant*5	Compliant*5
	Pin Type	-	-

★★: Under Development ★: New Products [Non-Recommended]: Please refrain from adopting newly.

■ Type Name Definition of DIPIPM™



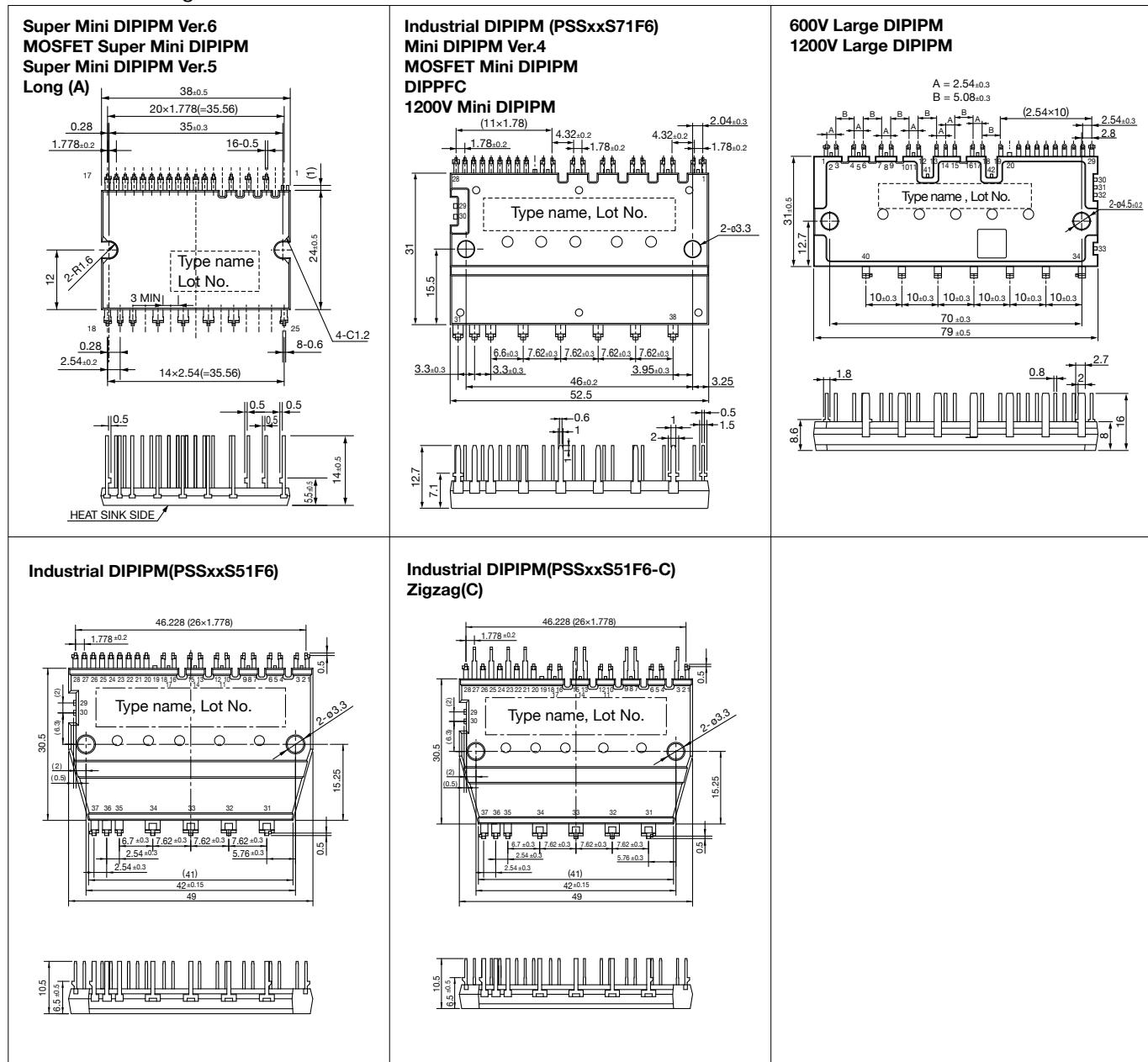
[Term] CSTBT™: Carrier Stored Trench-Gate Bipolar Transistor
 BSD: Bootstrap Diode, HVIC: High Voltage IC, LVIC: Low Voltage IC,
 UV: Supply Under Voltage protection,
 SC: Short Circuit protection, OT: Over-Temperature protection,
 RoHS: Restriction of hazardous substances in electrical and electronic equipment

[Notes] *1: PSSxxS92E6 has OT function, PSSxxS92F6 has VOT function
 *2: Analog temperature output
 *3: AC60Hz, 1minute. Corresponds to isolation voltage 2500Vrms in the case the convex-shaped heat sink
 *4: High melting point solder (Lead Over 85%) is used for chip soldering of PSSxxS51F6 only.
 *5: Pin plating and Chip soldering : Lead-free solder
 *6: High melting point solder (Lead Over 85%) is used for chip soldering only and Pin plating is Lead-free.
 *7: Molding resin insulation for PSSxxS51F6/-C

Line-up of DIPIPM™

Outline Drawing of DIPIPM™

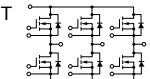
Unit:mm



Line-up of MOSFET Modules

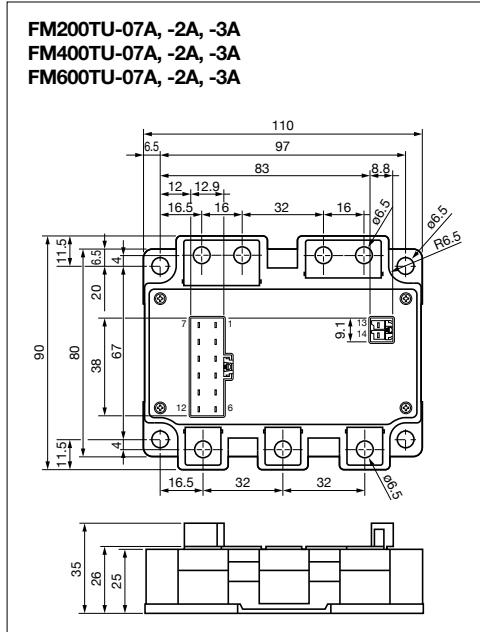
■ Series Matrix of MOSFET Modules

RoHS Directive Compliant

V _{DSS} I _D (A)	75V	Connection	100V	Connection	150V	Connection
100	FM200TU-07A	T	FM200TU-2A	T	FM200TU-3A	T
200	FM400TU-07A	T	FM400TU-2A	T	FM400TU-3A	T
300	FM600TU-07A	T	FM600TU-2A	T	FM600TU-3A	T
Connection						

■ Outline Drawing of MOSFET Modules

Unit: mm



Line-up of IPM

■ Series Matrix of 600V IPM (No.: Number of Outline Drawing, see page 7)

V _{CES} (V) I _C (A)	600V																
	L1 Series			S1 Series			V1 Series			Photovoltaic			L Series			S-DASH Series	
	Connection	No.		Connection	No.		Connection	No.		Connection	No.		Connection	No.		Connection	No.
50	PM50CL1A060	C 01	PM50CS1D060	05					PM50B4LA060	B4 01					PM50CSD060	C	
	PM50CL1B060	C 02							PM50B5LA060	B5 01					PM50CSE060	C	
	PM50RL1A060	R 01							PM50B6LA060	B6 01	PM50CLA060	C			PM50RSD060	R	
	PM50RL1B060	R 02							PM50B4LB060	B4 02	PM50CLB060	C			PM50RSE060	R	
	PM50RL1C060	R 03							PM50B5LB060	B5 02	PM50RLA060	R			PM50RLB060	R	
									PM50B6LB060	B6 02	PM50B4L1C060	B4 03			PM50B5L1C060	B5 03	
75	PM75CL1A060	C 01	PM75CS1D060	05					PM75B4LA060	B4 01					PM75CSD060	C	
	PM75CL1B060	C 02							PM75B5LA060	B5 01					PM75CSE060	C	
	PM75RL1A060	R 01							PM75B6LA060	B6 01	PM75CLA060	C			PM75RSD060	R	
	PM75RL1B060	R 02							PM75B4LB060	B4 02	PM75CLB060	C			PM75RSE060	R	
									PM75B5LB060	B5 02	PM75RLA060	R			PM75B6LB060	B6 02	
									PM75B4L1C060	B4 03	PM75B5L1C060	B5 03			PM75B6L1C060	B6 03	
100	PM100CL1A060	C 01	PM100CS1D060	C 05									PM100CLA060	C	PM100CSD060	C	
	PM100CL1B060	C 02											PM100CSE060	R	PM100RSD060	C	
	PM100RL1A060	R 01											PM100RLA060	R	PM100RSE060	R	
	PM100RL1B060	R 02															
150	PM150CL1A060	C 01	PM150CS1D060	C 05									PM150CLA060	C	PM150CSD060	C	
	PM150CL1B060	C 02											PM150CSE060	R	PM150RSD060	C	
	PM150RL1A060	R 01											PM150RLA060	R	PM150RSE060	R	
	PM150RL1B060	R 02															
200	PM200CL1A060	C 04	PM200CS1D060	C 05									PM200CLA060	C	PM200CSD060	C	
	PM200RL1A060	R 04											PM200CSE060	R	PM200RSD060	R	
300	PM300CL1A060	C 04											PM300CLA060	C	PM300CSD060	C	
	PM300RL1A060	R 04											PM300RLA060	R	PM300CSE060	R	
400/450					PM400DV1A060	D 06							PM450CLA060	C 08			
600					PM600DV1A060	D 06							PM600CLA060	C 08			
800					PM800DV1B060	D 07											
IGBT Chip	CSTBT ^{*1} Built-in Emitter Sensor Built-in Temperature Sensor		CSTBT ^{*1} Built-in Emitter Sensor Built-in Temperature Sensor		CSTBT ^{*1} Built-in Emitter Sensor Built-in Temperature Sensor		CSTBT ^{*1} Built-in Emitter Sensor Built-in Temperature Sensor		CSTBT ^{*2} Built-in Emitter Sensor Built-in Temperature Sensor		Planar Built-in Emitter Sensor						
Fault Output	UV	P-side/N-side	N-side		P-side/N-side		P-side/N-side		P-side/N-side	P-side/N-side		N-side ^{*3}					
	OT	P-side/N-side	N-side		P-side/N-side		P-side/N-side		P-side/N-side	P-side/N-side		N-side					
	SC	P-side/N-side	N-side		P-side/N-side		P-side/N-side		P-side/N-side	P-side/N-side		N-side ^{*3}					
	OC	-	-		-		-		-	-		N-side ^{*3}					
RoHS Directive	Compliant		Compliant		Compliant		Compliant		Compliant		Compliant		Compliant		Compliant		
Compatibility	L Series		S-DASH SERVO		V Series		-		-		-		-		-		
Connection	D	B4	B5	B6	C	R											

[Term] UV: Supply Under Voltage-lock protection, SC: Short-Circuit Protection, OT: Over-temperature protection,
OC: Over-current protection, CSTBT™: Carrier Stored Trench-Gate Bipolar Transistor.

Non-Recommended : Please refrain from adopting newly.

★: New Products

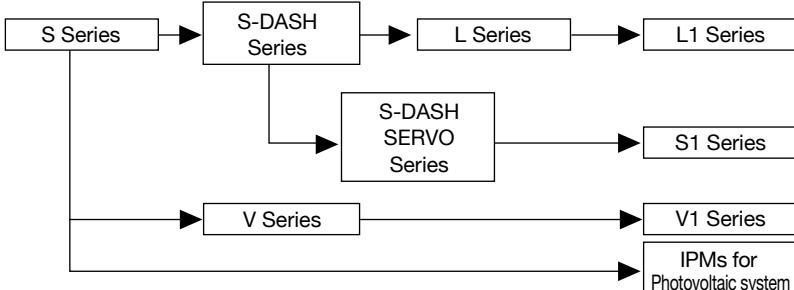
[Notes] *1: Full-gate CSTBT™ *2: PCM (Plugged Cell Merged) CSTBT™ *3: CSD/RSD have P-side

■ Type Name Definition of IPM

PM 100 R L1 A 120

- Voltage class
- Outline drawing and other specifications
- Series name
- Connection type
- Rated current capacity
- IPM

■ Evolution of IPM Series



■ Series Matrix of 1200V IPM (No.: Number of Outline Drawing, see page 7)

Vces (V)	1200V													
Series Ic (A)	L1 Series			S1 Series			V1 Series			L Series			S-DASH Series	
	Connection	No.	Connection	No.	Connection	No.	Connection	No.	Connection	No.	Connection	No.	Connection	
25	PM25CL1A120	C 01	PM25CS1D120	C 05						PM25CLA120	C			
	PM25CL1B120	C 02												
	PM25RL1A120	R 01												
	PM25RL1B120	R 02												
	PM25RL1C120	R 03												
50	PM50CL1A120	C 01	PM50CS1D120	C 05						PM50CLA120	C	PM50CSD120	C	
	PM50CL1B120	C 02												
	PM50RL1A120	R 01												
	PM50RL1B120	R 02												
75	PM75CL1A120	C 01	PM75CS1D120	C 05						PM75CLA120	C	PM75CSD120	C	
	PM75CL1B120	C 02												
	PM75RL1A120	R 01												
	PM75RL1B120	R 02												
100	PM100CL1A120	C 04	PM100CS1D120	C 05						PM100CLA120	C	PM100CSD120	C	
	PM100RL1A120	R 04												
150	PM150CL1A120	C 04								PM150CLA120	C	PM150CSD120	C	
	PM150RL1A120	R 04												
200							PM200DV1A120	D 06	PM200CLA120	C 08				
300							PM300DV1A120	D 06	PM300CLA120	C 08				
450							PM450DV1A120	D 06	PM450CLA120	C 08				
IGBT Chip	CSTBT ^{*1} Built-in Current Sensor Built-in Temperature Sensor			CSTBT ^{*1} Built-in Current Sensor Built-in Temperature Sensor			CSTBT ^{*1} Built-in Current Sensor Built-in Temperature Sensor			CSTBT ^{*2} Built-in Current Sensor Built-in Temperature Sensor		Planar Built-in Current Sensor		
Fault Output	UV	P-side/N-side		N-side			P-side/N-side		P-side/N-side		N-side ^{*3}			
	OT	P-side/N-side		N-side			P-side/N-side		P-side/N-side		N-side			
	SC	P-side/N-side		N-side			P-side/N-side		P-side/N-side		N-side ^{*3}			
	OC	-		-			-		-		N-side ^{*3}			
RoHS Directive	Compliant		Compliant		Compliant		Compliant		Compliant		Compliant			
Compatibility	L Series		S-DASH SERVO		V Series		-		-		-			
Connection	D		C		R									

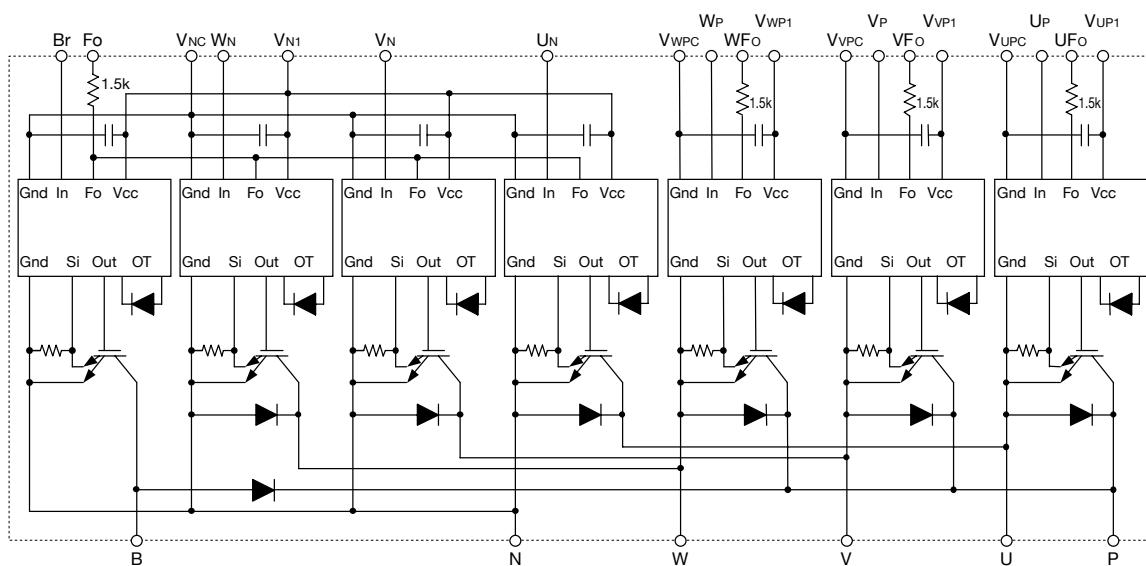
[Term] UV: Supply Under Voltage-lock protection, SC: Short-Circuit Protection, OT: Over-temperature protection,
OC: Over-current protection, CSTBT™: Carrier Stored Trench-Gate Bipolar Transistor.

Non-Recommended : Please refrain from adopting newly.

RoHS: Restriction of hazardous substances in electrical and electronic equipment

[Notes] *1: Full-gate CSTBT™ *2: PCM (Plugged Cell Merged) CSTBT™ *3: CSD/RSD have P-side

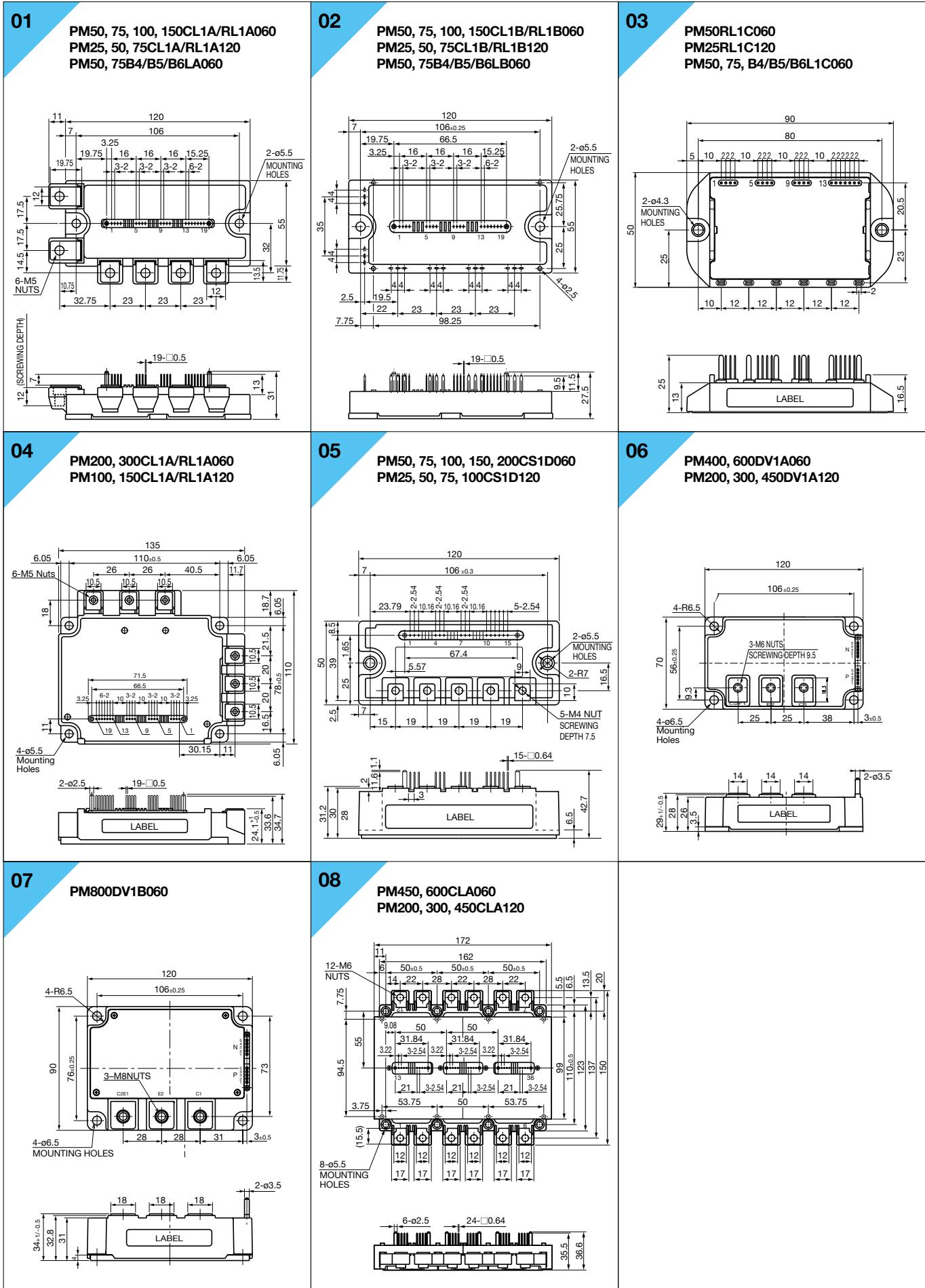
Equivalent circuit of PM100RL1A060



Line-up of IPM

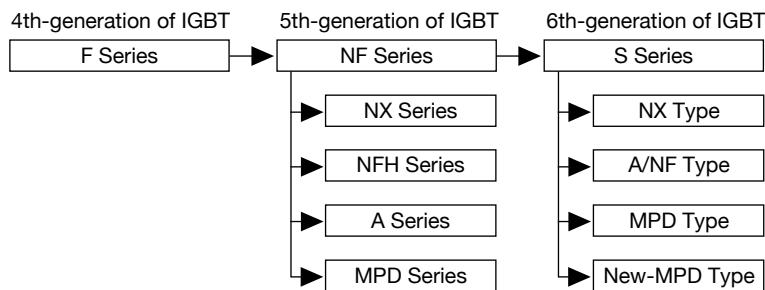
Outline Drawing of IPM

Unit: mm



Line-up of IGBT Modules

Evolution of IGBT Module Series



Type Name Definition of IGBT Modules

CM 150 D Y -24 NF

- Series name
- Voltage class
- Outline drawing and other specifications
- Connection type
- Rated current capacity
- IGBT Module

Features of IGBT Module Series

S Series

- Lineup includes various package types.
- 6th-generation CSTBT™ delivers low-loss performance.
- Thinner package. (Height: 17mm) (NX type)
- Suited to large-capacity applications
(2500A/1200V, 1800A/1700V) (New-MPD type)

MPD: Mega Power Dual

NFH Series

- High-speed CSTBT™ delivers low-loss performance.
- Soft switching (resonant) turn-off function (ZVS)
- Enhanced inner wiring (skin effect)

CSTBT™: Carrier Stored Trench-Gate Bipolar Transistor.
Our unique IGBT that makes use of the carrier cumulative effect.

Series Matrix of 600V IGBT Modules (No.: Number of Outline Drawing, see page 13 to 16)

RoHS Directive Compliant

V _{ces} (V)	600V										RoHS Directive Compliant		
Series	5th-generation NX Series			NF Series			NFH Series			F Series			
I _c (A)	Connection	No.	Connection	No.	Connection	No.	Connection	No.	Connection	No.	Connection	No.	
75	CM75MX-12A	M	01	CM75TL-12NF CM75RL-12NF	T R	08 08				CM75DU-12F CM75TU-12F	D T	14 17	
100	CM100MX-12A CM100RX-12A	M R	01 02	CM100TL-12NF CM100RL-12NF	T R	08 08	CM100DUS-12F	D	14	CM100DU-12F CM100TU-12F	D T	14 17	
150	CM150RX-12A	R	02	CM150DY-12NF CM150TL-12NF CM150RL-12NF	D T R	09 08 08	CM150DUS-12F	D	14	CM150DU-12F CM150TU-12F	D T	14 18	
200	CM200RX-12A	R	02	CM200DY-12NF CM200TL-12NF CM200RL-12NF	D T R	09 10 10	CM200DU-12NFH	D	14	CM200DU-12F CM200TU-12F	D T	14 18	
300	CM300DX-12A	D	03	CM300DY-12NF	D	09	CM300DU-12NFH	D	15	CM300DU-12F	D	15	
400	CM400DX-12A	D	03	CM400DY-12NF	D	11	CM400DU-12NFH	D	15	CM400DU-12F	D	15	
600	CM600HX-12A	H	04	CM600DY-12NF	D	12	CM600DU-12NFH	D	16	CM600HU-12F	H	20	
Connection	H		D		T		R		M				

[Non-Recommended] : Please refrain from adopting newly.

Line-up of IGBT Modules

■ Series Matrix of 6th/6.1th-generation of IGBT Modules <S Series> 1200V/1700V (No.: Number of Outline Drawing, see page 13 to 16)
RoHS Directive Compliant

V _{CES} (V)	Series	1200V								1700V								
		NX Type		A/NF Type		MPD Type		New-MPD Type		NX Type		MPD Type		New-MPD Type				
Ic		Connection No.		Connection No.		Connection No.		Connection No.		Connection No.		Connection No.		Connection No.		Connection No.		
35	CM35Mxa-24S	M	05															
50	CM50Mxa-24S	M	05															
75	CM75Mxa-24S	M	05															
	CM75Tx-24S	T	06															
	CM75Rx-24S	R	02															
100	CM100Mxa-24S	M	05															
	CM100Tx-24S1*	T	33															
	CM100Tx-24S	T	06															
	CM100Rx-24S1*	R	34															
	CM100Rx-24S	R	02															
150	CM150Dx-24S	D	03															
	CM150Exs-24S	E	32															
	CM150Tx-24S1*	T	33															
	CM150Tx-24S	T	06															
	CM150Rx-24S1*	R	34															
	CM150Rx-24S	R	02															
200	CM200Dx-24S	D	03															
	CM200Exs-24S	E	32															
	CM200Rxl-24S	R	29															
225	CM225Dx-24S1*	D	35															
300	CM300Dx-24S1*	D	35	CM300Dy-24S	D	11												
	CM300Dx-24S	D	03															
	CM300Exs-24S	E	32															
400				CM400C1Y-24S	C	12												
450	CM450Dx-24S1*	D	35															
	CM450Dx-24S	D	03	CM450Dy-24S	D	12												
600	CM600Dx-24S1*	D	35	CM600Dy-24S	D	12												
	CM600Dxl-24S	D	07															
800				CM800Dy-24S	D	13												
900							CM900DUC-24S*	D	24									
1000	CM1000Dxl-24S	D	07													CM1000DUC-34SA	D	24
1400							CM1400DUC-24S	D	24									
1800																CM1800Dy-34S	D	26
2500								CM2500Dy-24S*	D	26								
Connection		C1		D		T		R		M								

Non-Recommended : Please refrain from adopting newly.

★★: Under Development ★: New Products ★▼: UL unauthenticated

■ Series Matrix of 5th-generation IGBT Modules 1200V/1700V (No.: Number of Outline Drawing, see page 13 to 16)

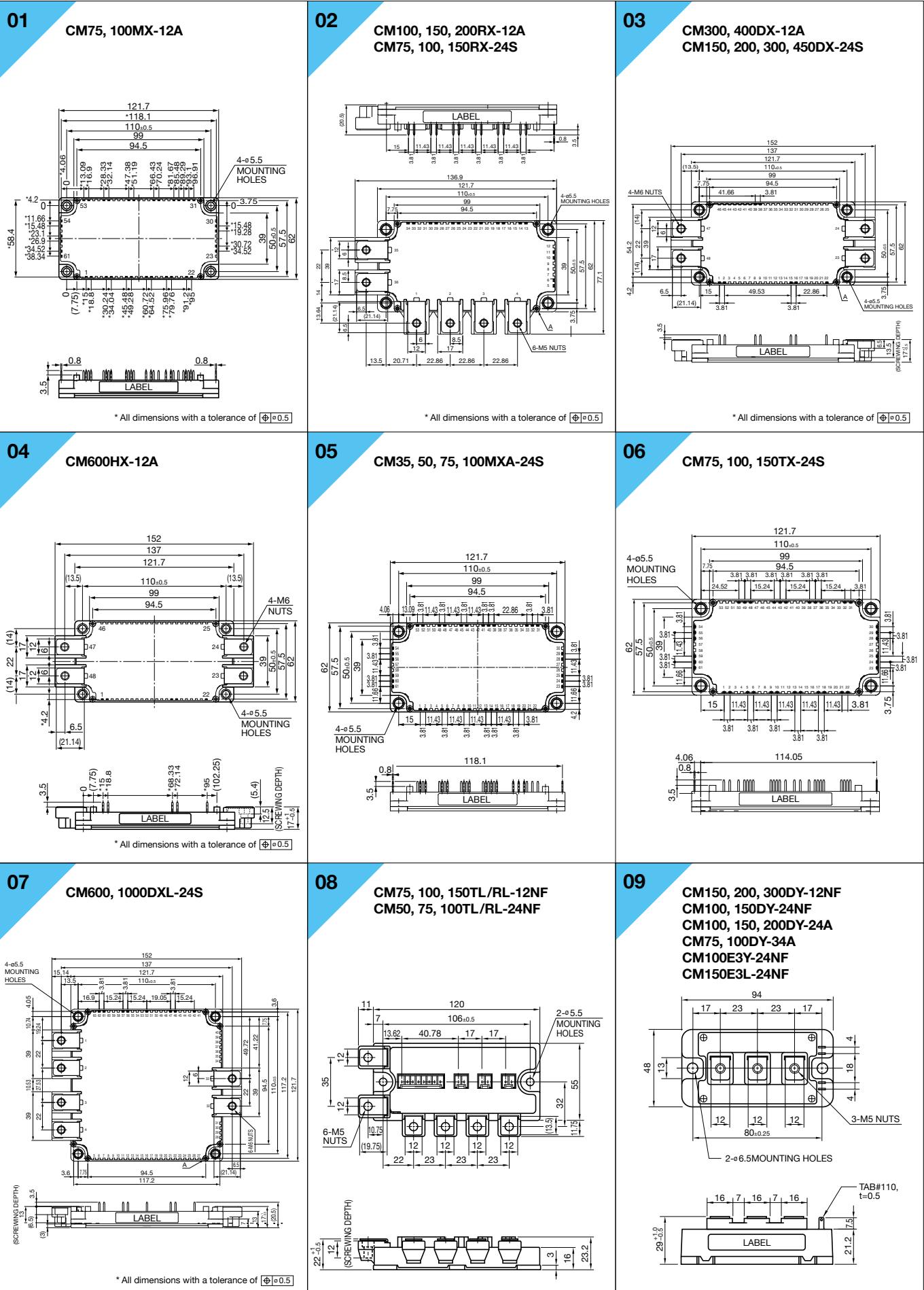
RoHS Directive Compliant

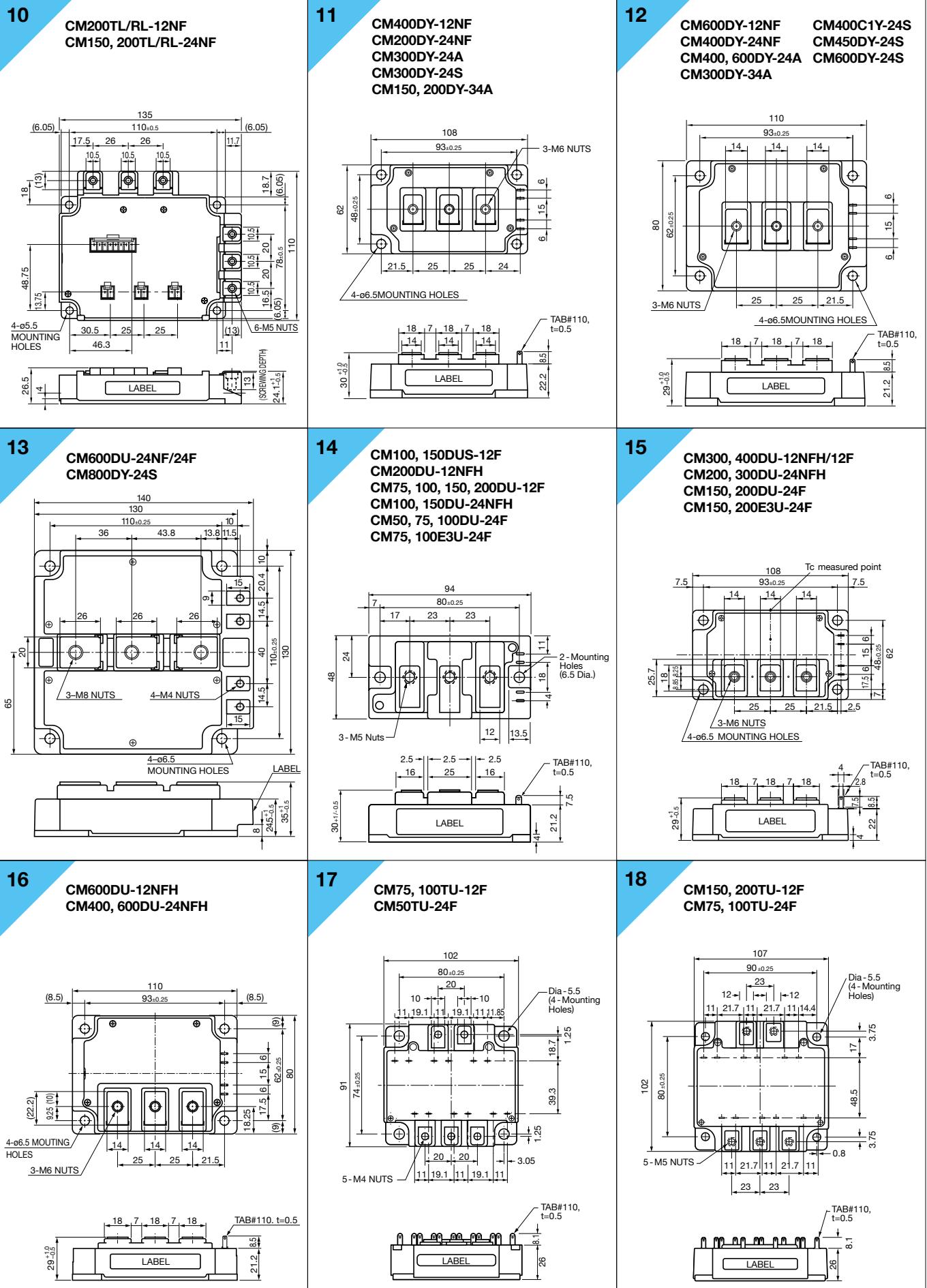
V _{CES(V)} I _c	1200V										1700V			
	NF Series			A Series		NFH Series			F Series		A Series			
	Connection	No.	Connection	No.	Connection	No.	Connection	No.	Connection	No.	Connection	No.	Connection	No.
50	CM50TL-24NF	T 08							CM50DU-24F	D 14				
	CM50RL-24NF	R 08							CM50TU-24F	T 17				
75	CM75TL-24NF	T 08							CM75DU-24F	D 14				
	CM75RL-24NF	R 08							CM75TU-24F	T 18	CM75DY-34A	D 09		
100	CM100DY-24NF	D 09							CM100DU-24F	D 14				
	CM100E3Y-24NF	E3 09	CM100DY-24A	D 09	CM100DU-24NFH	D 14	CM100TU-24F	T 18	CM100DY-34A	D 09				
	CM100TL-24NF	T 08							CM100E3U-24F	E3 14				
	CM100RL-24NF	R 08												
150	CM150DY-24NF	D 09							CM150DU-24F	D 15				
	CM150E3L-24NF	E3 09	CM150DY-24A	D 09	CM150DU-24NFH	D 14	CM150E3U-24F	E3 15	CM150DY-34A	D 11				
	CM150TL-24NF	T 10												
	CM150RL-24NF	R 10												
200	CM200DY-24NF	D 11							CM200DU-24F	D 15				
	CM200TL-24NF	T 10	CM200DY-24A	D 09	CM200DU-24NFH	D 15	CM200E3U-24F	E3 15	CM200DY-34A	D 11				
	CM200RL-24NF	R 10												
300			CM300DY-24A	D 11	CM300DU-24NFH	D 15	CM300DU-24F	D 19	CM300DY-34A	D 12				
400	CM400DY-24NF	D 12	CM400HA-24A	H 21	CM400DU-24NFH	D 16	CM400HU-24F	H 20	CM400DY-34A	D 25				
			CM400DY-24A	D 12			CM400DU-24F	D 22						
500											CM500HA-34A	H 21		
600	CM600DU-24NF	D 13	CM600HA-24A	H 21	CM600DU-24NFH	D 16	CM600HU-24F	H 23						
			CM600DY-24A	D 12			CM600DU-24F	D 13						
Connection		H		D		T		R						

Line-up of IGBT Modules

Outline Drawing of IGBT Modules

Unit: mm

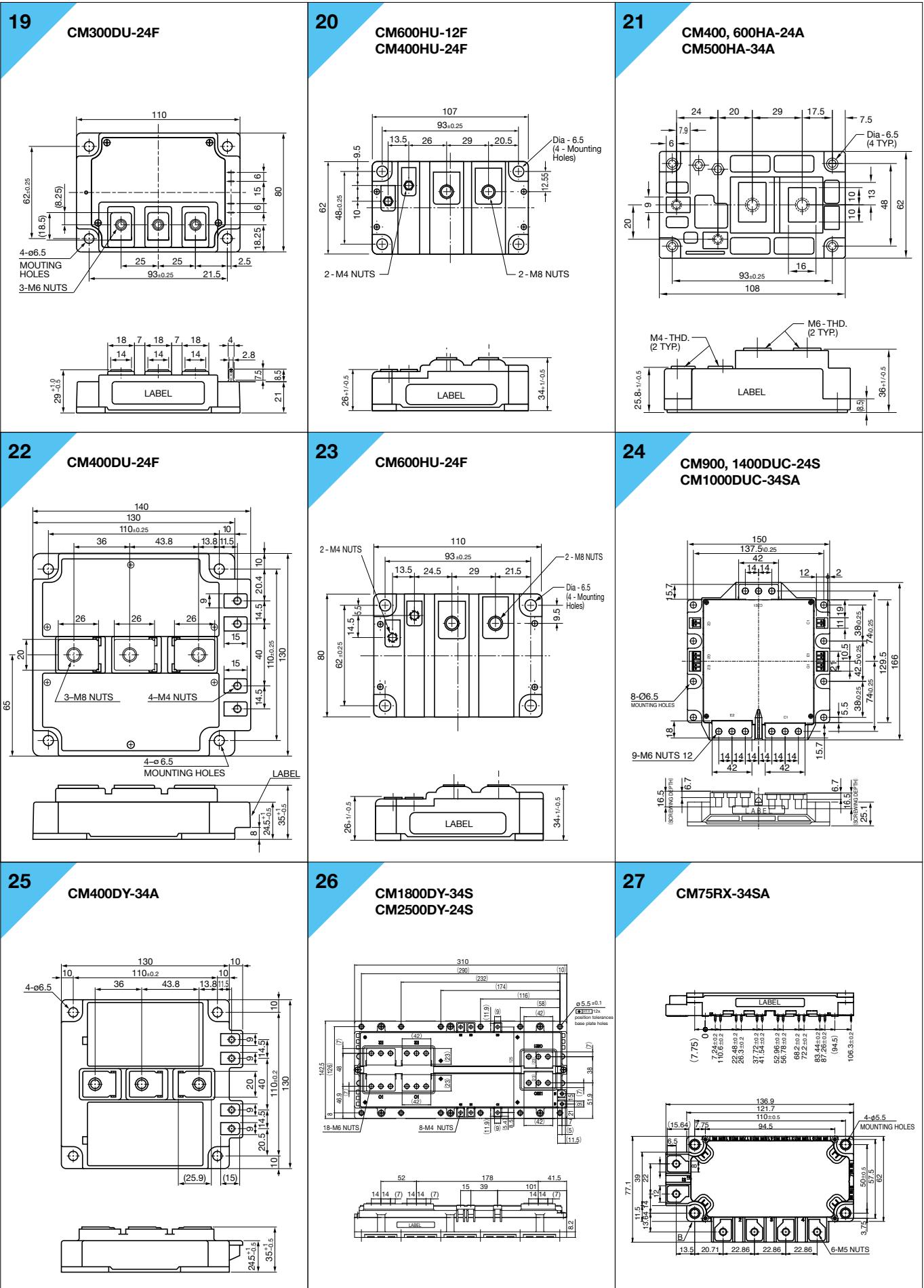




Line-up of IGBT Modules

Outline Drawing of IGBT Modules

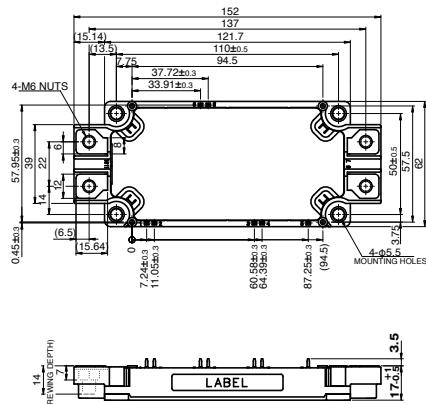
Unit: mm



Unit:mm

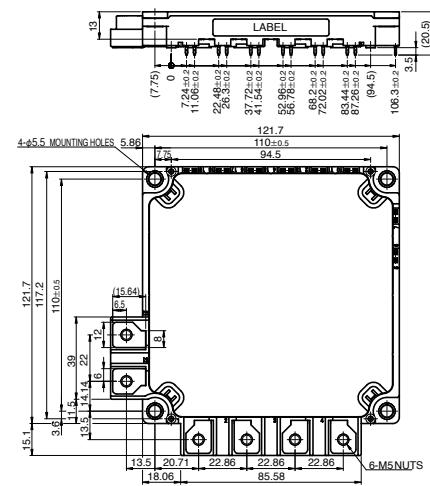
28

**CM150DX-34SA
CM200DX-34SA
CM300DX-34SA**



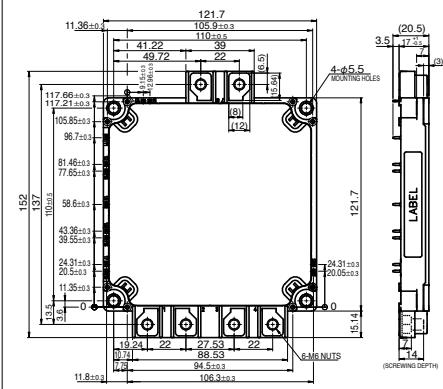
29

**CM200RXL-24S
CM150RXL-34SA**



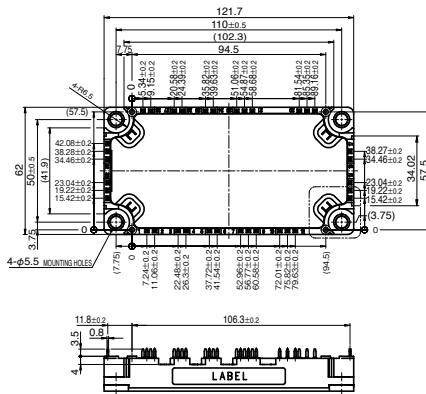
30

**CM450DXL-34SA
CM600DXL-34SA**



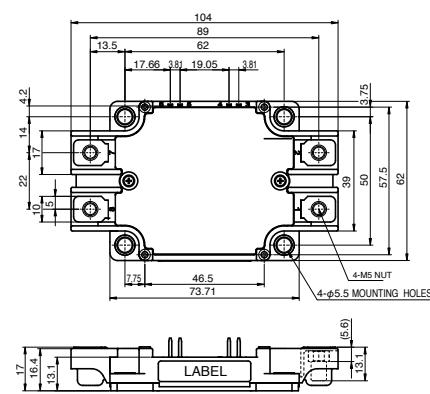
31

CM75MXA-34SA



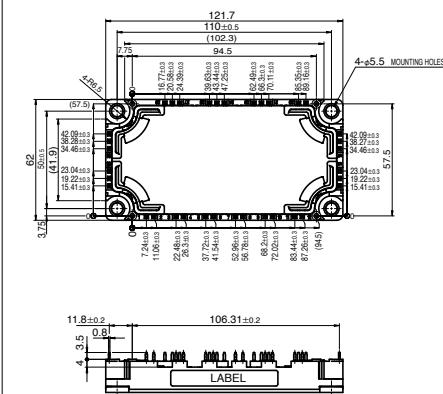
32

**CM150EXS-24S
CM200EXS-24S
CM300EXS-24S
CM200EXS-34SA**



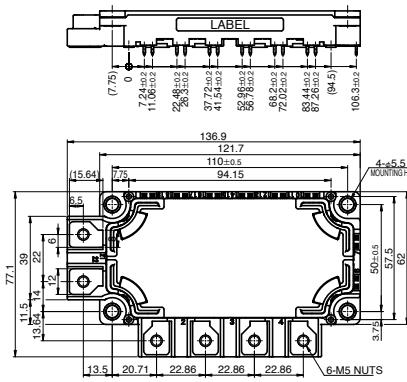
33

**CM100TX-24S1
CM150TX-24S1**



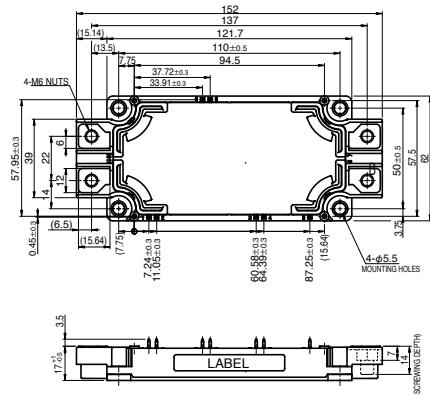
34

**CM100RX-24S1
CM150RX-24S1**



35

**CM225DX-24S1
CM300DX-24S1
CM450DX-24S1
CM600DX-24S1**



Line-up of HV Modules

■ Series Matrix of HVIGBT/HVIPM (No.: Number of Outline Drawing, see page 16 and 17)

V _{CES} I _{C(A)}	1700V			2500V			3300V			4500V			6500V			
	Connection	Type	No.	Connection	Type	No.	Connection	Type	No.	Connection	Type	No.	Connection	Type	No.	
200														CM200HG-130H	H HG 07	
400				CM400DY-50H	D HA	15	CM400HG-66H CM400DY-66H	H D HA	07 15	CM400HB-90H	H HB	03	CM400HG-130H CM400E2G-130H CM400E4G-130H	H HG E2 E4 09 09		
600	CM600DY-34H CM600E2Y-34H	D E2	HA 01							CM600HG-90H CM600HB-90H	H HG	12 03	CM600HG-130H	H HG 09		
750														CM750HG-130R★	H HG 11	
800	CM800DZB-34N CM800DZ-34H CM800HA-34H	D D H	NB HC HA	01 01 -	CM800HB-50H CM800HA-50H	H H	HB HA	03 -	CM800HC-66H CM800E4C-66H CM800E6C-66H CM800HB-66H CM800HA-66H	H E4 E2 H H	HC HC HB HA	03 06 06 03 -	CM800HC-90R★ CM800HG-90R★	H R RG 08 13		
900													CM900HG-90H CM900HC-90H CM900HB-90H	H HG H HC H HB 09 06 06		
1000										CM1000HC-66R★ CM1000E4C-66R★	H E4	R R	08 10			
1200	CM1200HCB-34N CM1200DB-34N CM1200DC-34N CM1200E4C-34N CM1200HC-34H CM1200DC-34S★	H D D E4 H D	NB N N N S	03 04 04 05 02 04	CM1200HC-50H CM1200HB-50H CM1200HA-50H	H H H	HC HB HA	06 06 -	CM1200HG-66H CM1200HC-66H CM1200HB-66H CM1200HA-66H PM1200HCE330-1	H H H H	HG HC HB HA	09 06 06 -	CM1200HC-90R★ CM1200HC-90RA CM1200HG-90R★	H R R RG 10 10 11		
1500										CM1500HC-66R CM1500HG-66R★	H H	R RG	10 11			
1600	CM1600HC-34H	H	HC	02												
1800	CM1800HCB-34N CM1800HC-34N CM1800HC-34H	H H H	NB N HC	06 05 06												
2400	CM2400HCB-34N CM2400HC-34N CM2400HC-34H	H H H	NB N HC	06 05 06												
Connection	H			E2/E6			E4			D						

[Type Description] (H Series: standard) HA: Cu Base plate, HB: Cu Base plate, HC: AISIC Base plate, HG: AISIC Base plate

Non-Recommended : Please refrain from adopting newly.

(N Series: CSTBT™) N: AISIC Base plate (CM1200DB-34N: Cu Base plate), NB: AISIC Base plate (Outline of H Series)

★★: Under Development ★: New Products

(R Series: Low Loss) R: AISIC Base plate, RG: AISIC Base plate

(S Series: CSTBT™ (III)) S: AISIC Base plate

*: High-Insulation Package (10.2kV, AC 1min.)

■ Series Matrix of HVDIODE Modules (No.: Number of Outline Drawing, see page 18)

V _{PBM} I _{F(A)}	1700V			3300V			4500V			6500V		
	Connection	Type	No.	Connection	Type	No.	Connection	Type	No.	Connection	Type	No.
200										RM200DG-130S	D SG	18
250										RM250DG-130F★	D FG	18
300							RM300DG-90S	D SG	18			
400				RM400DG-66S RM400DY-66S	D SG SD	18 19	RM400DG-90F★	D FG	18			
600				RM600DY-66S	D SD	19	RM600HE-90S	H SH	17	RM600DG-130S	D SG	18
800							RM800DG-90F★	D FG	18			
900							RM900HC-90S RM900DB-90S	H SH SD	21 21			
1000				RM1000DC-66F★	D F	20						
1200	RM1200DB-34S	D SD	16	RM1200DG-66S RM1200HE-66S RM1200DB-66S	D SG SD	18 17 21	RM1200DG-90F★	D FG	18			
1500				RM1500DC-66F★	D F	20						
1800	RM1800HE-34S	H SH	17									
Connection	H			D								

[Type Description] (F Series: Low Loss) F: AISIC Base plate, FG: AISIC Base plate

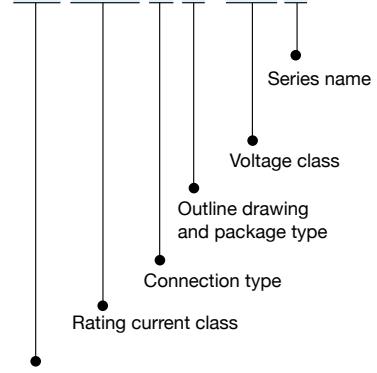
★★: Under Development ★: New Products

(S Series: standard) SH: AISIC Base plate, SD: Cu Base plate, SG*: AISIC Base plate

*: High-Insulation Package (10.2kV, AC 1min.)

■ Type Name Definition of IGBT Modules

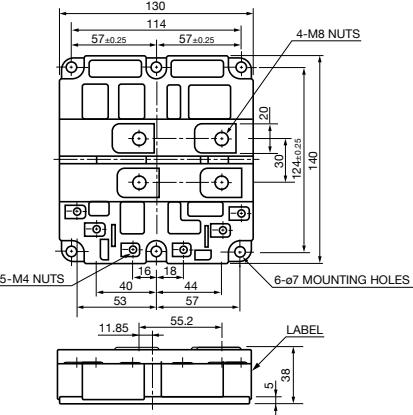
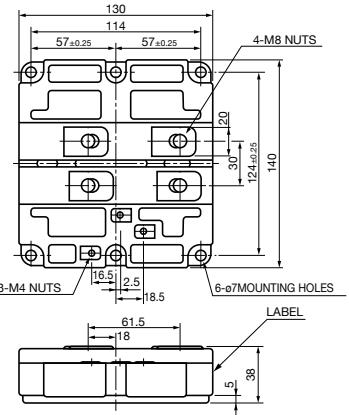
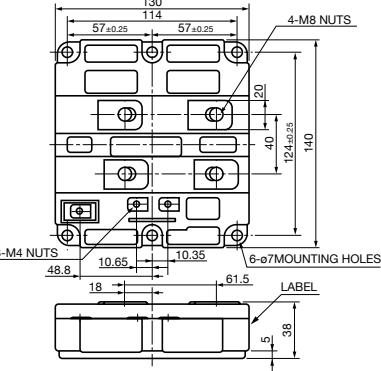
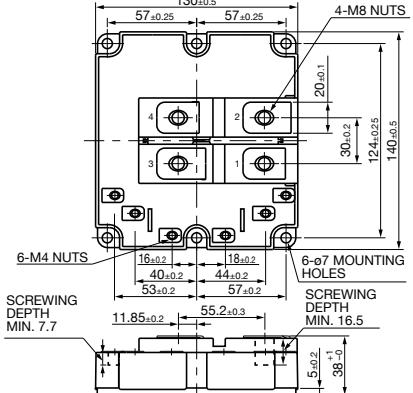
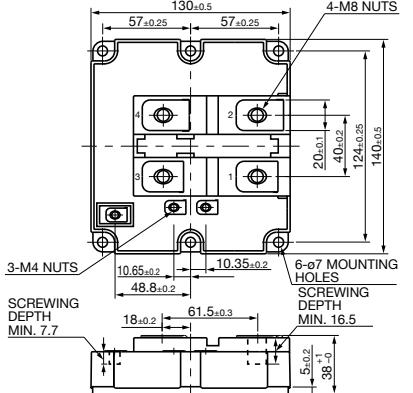
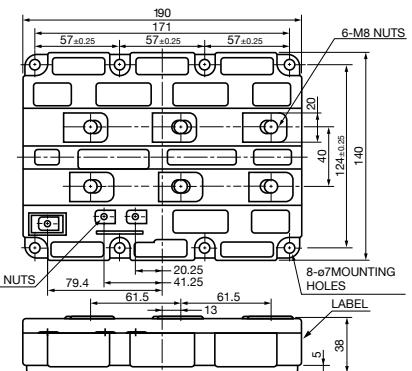
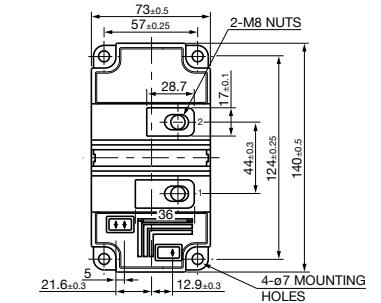
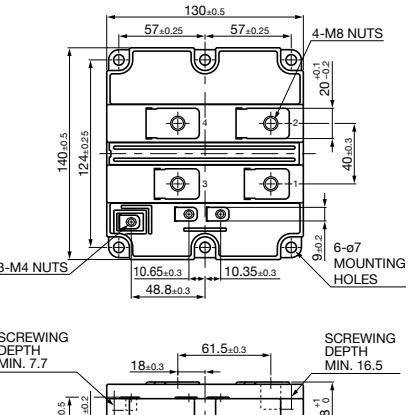
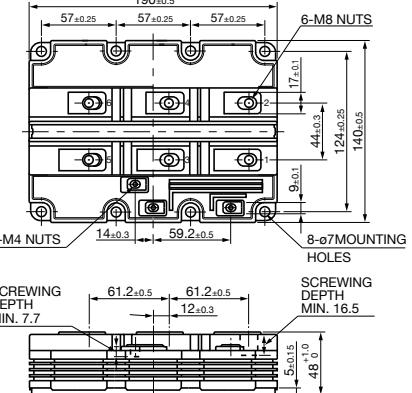
CM 1200 H C -66 H



CM: IGBT, RM: DIODE, PM: HVIPM

■ Outline Drawing of HVIGBT Modules/HVIPM

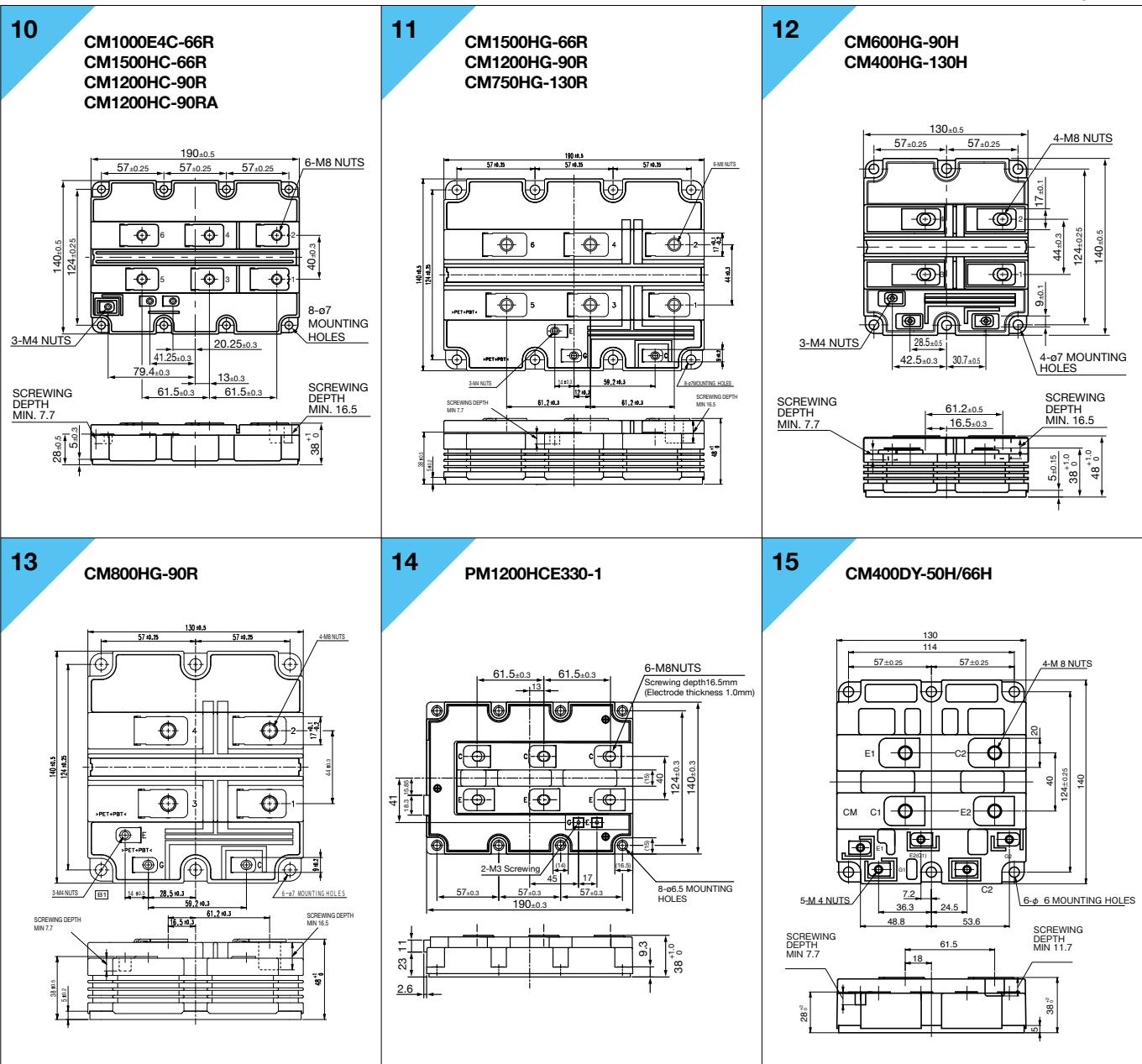
Unit: mm

<p>01 CM600DY-34H CM600E2Y-34H CM800DZ-34H CM800DZB-34N</p>  <p>4-M8 NUTS 5-M4 NUTS 6-67 MOUNTING HOLES 11.85 ± 0.2 55.2 LABEL 130 114 57 ± 0.25 57 ± 0.25 20 124 ± 0.25 140 16 18 40 44 53 57 30 30.2 124 ± 0.25 140 ± 0.5 11.85 ± 0.2 55.2 ± 0.2 38 5</p>	<p>02 CM1200, 1600HC-34H</p>  <p>4-M8 NUTS 3-M4 NUTS 6-67 MOUNTING HOLES LABEL 130 114 57 ± 0.25 57 ± 0.25 20 124 ± 0.25 140 16.5 2.5 18.5 61.5 18 30 30.2 124 ± 0.25 140 ± 0.5 18 61.5 5 38</p>	<p>03 CM1200HCB-34N CM800HB-50H, -66H CM800HC-66H CM400, 600HB-90H</p>  <p>4-M8 NUTS 3-M4 NUTS 6-67 MOUNTING HOLES LABEL 130 114 57 ± 0.25 57 ± 0.25 20 124 ± 0.25 140 10.65 10.35 48.8 18 61.5 30 30.2 124 ± 0.25 140 ± 0.5 18 61.5 5 38</p>
<p>04 CM1200DB/DC-34N CM1200DC-34S</p>  <p>4-M8 NUTS 6-M4 NUTS SCREWING DEPTH MIN. 7.7 6-67 MOUNTING HOLES 11.85 ± 0.2 55.2 ± 0.3 SCREWING DEPTH MIN. 16.5 130 ± 0.5 57 ± 0.25 20 ± 0.1 124 ± 0.25 140 ± 0.5 16 ± 0.2 40 ± 0.2 44 ± 0.2 53 ± 0.2 57 ± 0.2 30 ± 0.2 30.2 124 ± 0.25 140 ± 0.5 11.85 ± 0.2 55.2 ± 0.3 38 ± 0.2 5 38 ± 0.2</p>	<p>05 CM1200E4C-34N CM1800, 2400HC-34N</p>  <p>4-M8 NUTS 3-M4 NUTS SCREWING DEPTH MIN. 7.7 6-67 MOUNTING HOLES 130 ± 0.5 57 ± 0.25 20 ± 0.1 124 ± 0.25 140 ± 0.5 10.65 ± 0.2 10.35 ± 0.2 48.8 ± 0.2 18 ± 0.2 61.5 ± 0.3 30 ± 0.2 30.2 124 ± 0.25 140 ± 0.5 18 ± 0.2 61.5 ± 0.3 5 ± 0.2 38 ± 0.2</p>	<p>06 CM1800, 2400HCB-34N CM1800, 2400HC-34H CM1200HB/HC-50H, -66H CM800E4C/E6C-66H CM900HB/HC-90H</p>  <p>6-M8 NUTS 3-M4 NUTS 8-67 MOUNTING HOLES LABEL 190 171 57 ± 0.25 57 ± 0.25 20 124 ± 0.25 140 20.25 41.25 61.5 13 61.5 79.4 13 61.5 5 38 190 ± 0.5 57 ± 0.25 57 ± 0.25 20 124 ± 0.25 140 14.03 59.2 ± 0.5 61.5 13 61.5 9.01 5 38</p>
<p>07 CM400HG-66H CM200HG-130H</p>  <p>2-M8 NUTS 4-67 MOUNTING HOLES 140 ± 0.5 21.6 ± 0.3 12.9 ± 0.3 SCREWING DEPTH MIN. 4 130 ± 0.5 57 ± 0.25 28.7 17 ± 0.1 4.03 124 ± 0.25 140 ± 0.5 16.2 ± 0.3 16.2 ± 0.3 5.8 36.2 5.9 48.10 28.0 ± 0.5 5.0 ± 0.2 18.0 ± 0.3 61.5 ± 0.3 18.0 ± 0.3 38.0 36.2 5.9 48.10 5.0 ± 0.2 18.0 ± 0.3 38.0</p>	<p>08 CM800HC-90R CM1000HC-66R</p>  <p>4-M8 NUTS 3-M4 NUTS 6-67 MOUNTING HOLES 130 ± 0.5 57 ± 0.25 20 ± 0.1 124 ± 0.25 140 ± 0.5 10.65 ± 0.3 10.35 ± 0.3 48.8 ± 0.3 18 ± 0.3 61.5 ± 0.3 30 ± 0.2 30.2 124 ± 0.25 140 ± 0.5 18 ± 0.3 61.5 ± 0.3 5 ± 0.2 38 ± 0.2</p>	<p>09 CM1200HG-66H CM900HG-90H CM400E2G/E4G-130H CM600HG-130H</p>  <p>6-M8 NUTS 3-M4 NUTS 8-67 MOUNTING HOLES SCREWING DEPTH MIN. 16.5 190 ± 0.5 57 ± 0.25 57 ± 0.25 20 124 ± 0.25 140 ± 0.5 14.03 59.2 ± 0.5 61.2 ± 0.5 12.0 ± 0.3 61.2 ± 0.5 9.01 5 38 190 ± 0.5 57 ± 0.25 57 ± 0.25 20 124 ± 0.25 140 ± 0.5 14.03 59.2 ± 0.5 61.2 ± 0.5 12.0 ± 0.3 61.2 ± 0.5 9.01 5 38</p>

Line-up of HV Modules

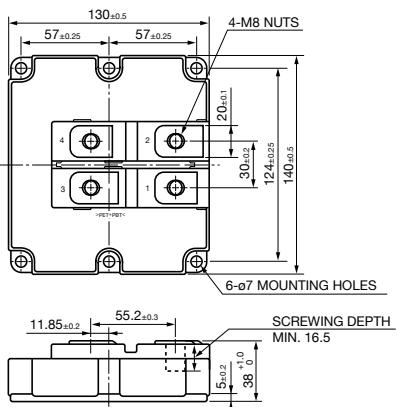
Outline Drawing of HVIGBT Modules / HVIPM

Unit: mm

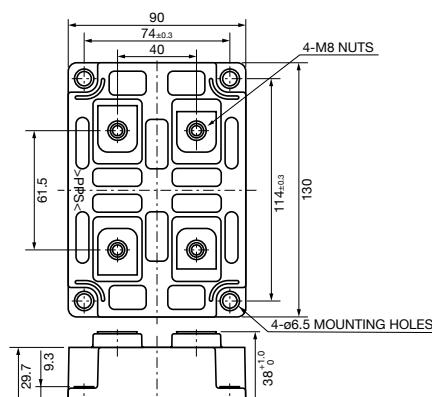


Unit: mm

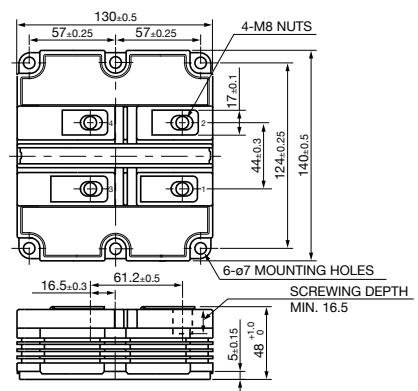
16 RM1200DB-34S



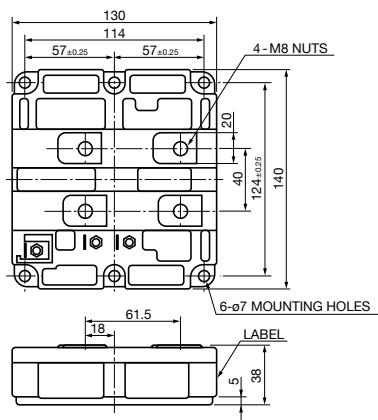
17 RM1800HE-34S
RM1200HE-66S
RM600HE-90S



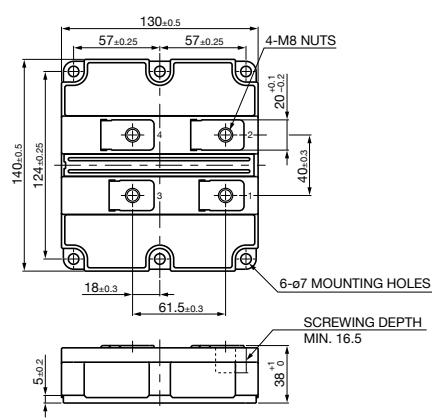
18 RM400, 1200DG-66S
RM300DG-90S
RM400, 800, 1200DG-90F
RM200, 600DG-130S
RM250DG-130F



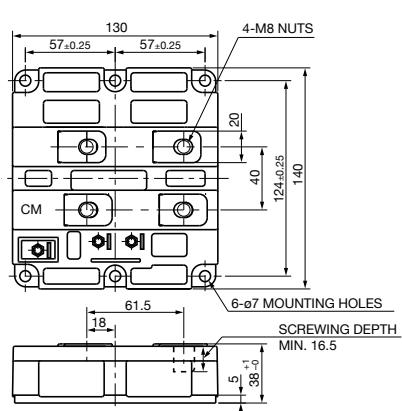
19 RM400, 600DY-66S



20 RM1000, 1500DC-66F



21 RM1200DB-66S
RM900DB/HC-90S



Power Modules for Electric and Hybrid Vehicles

Features

Common

- Long power/temperature cycle life
- High-precision on-chip temperature sensor
- High traceability in managing materials/components throughout the entire production process for each product

- Package structure compliant with the End-of-Life-Vehicles Directive, regulations relating to substances of environmental concern

J Series T-PM (Transfer-molded Power Module)

- Structure incorporates Transfer modeling and original direct lead bonding (DLB) technique
- DLB structure reduces internal wiring resistance and inductance
- Completely Pb-free (including the pins)

J1 Series (Power Module with Pin-fin)

- Direct cooling package with cooling fin
- Highly reliable DLB package for automotive inverters
- Low power loss 7th-generation CSTBT™ chip technology
- Compact, lightweight, high-power-density module

[Term] CSTBT™: Carrier Stored Trench-Gate Bipolar Transistor.

J Series IPM

- Drive circuit and protection circuits for short-circuiting, power supply* undervoltage and overheating
- Built-in Isolated Switching Power Supply for IGBT drive and IPM control functions (PM800CJG060G, PM500CJG120G)
- Redundancy function for failsafe design and high system performance, chip temperature analog output function and DC-link voltage analog output function (optional specifications)
- Built-in automotive grade photocouplers and interface connector(s)
- High noise tolerance as a result of built-in shield-plate and circuit pattern optimization

T-PM : Transfer-molded Power Module

Matrix of 650V and 900V Power Modules (No. : Number of Outline Drawing, please refer to page 22)

VCES(V)	650V								900V		
	Series	J1 Series			J Series					J1 Series	
		PM with Pin-Fin	Connection	No.	T-PM	Connection	No.	IPM	Connection	No.	
300	CT300CJ1A060**	C	01		CT300DJG060**	D	02	PM300CJG060G**	C	04	
400	-	-	-		-	-	-	-	-	-	CT400CJ1A090**
500	-	-	-		-	-	-	-	-	-	
600	CT600CJ1A060**	C	01		CT600DJH060**	D	03	PM600CJG060G**	C	05	
800	-	-	-		-	-	-	PM800CJG060G**	C	06	
Connection		C			D						

* PM : Power Module, ★★ Under Development

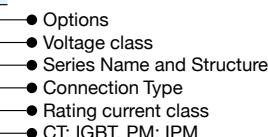
Matrix of 1200V Power Modules (No. : Number of Outline Drawing, please refer to page 22)

VCES(V)	1200V								
	Series	J1 Series			J Series				
		PM with Pin-Fin	Connection	No.	T-PM	Connection	No.	IPM	Connection
300	CT300CJ1A120**	C	01		CT300DJH120**	D	03	-	-
400	-	-	-		-	-	-	-	-
500	-	-	-		-	-	PM500CJG120G**	C	06
600	-	-	-		-	-	-	-	-
800	-	-	-		-	-	-	-	-
Connection		C			D				

* PM : Power Module, ★★ Under Development

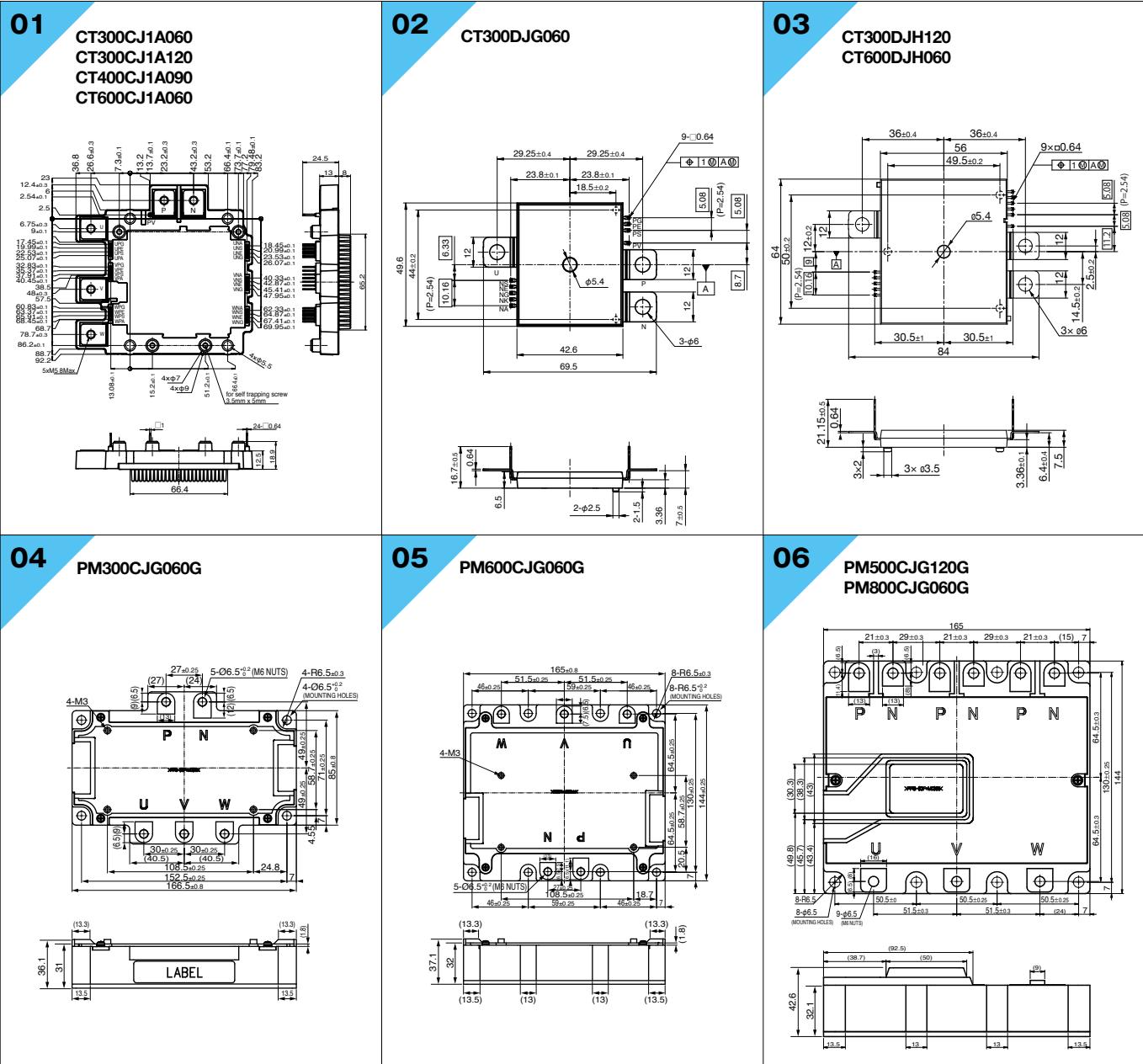
Type Name Definition of Power Modules for Electric and Hybrid Vehicles

PM 500 C JG 120 G



■ Outline drawing of Power Modules for Electric and Hybrid Vehicles

Unit:mm



POWER MODULES

Please visit our website for further details.

www.MitsubishiElectric.com

Keep safety first in your circuit designs!

- Mitsubishi Electric Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of non-flammable material or (iii) prevention against any malfunction or mishap.

Notes regarding these materials

- These materials are intended as a reference to assist our customers in the selection of the Mitsubishi semiconductor product best suited to the customer's application; they do not convey any license under any intellectual property rights, or any other rights, belonging to Mitsubishi Electric Corporation or a third party.
 - Mitsubishi Electric Corporation assumes no responsibility for any damage, or infringement of any third-party's rights, originating in the use of any product data, diagrams, charts, programs, algorithms, or circuit application examples contained in these materials.
 - All information contained in these materials, including product data, diagrams, charts, programs and algorithms represents information on products at the time of publication of these materials, and are subject to change by Mitsubishi Electric Corporation without notice due to product improvements or other reasons. It is therefore recommended that customers contact Mitsubishi Electric Corporation or an authorized Mitsubishi Semiconductor product distributor for the latest product information before purchasing a product listed herein.
- The information described here may contain technical inaccuracies or typographical errors. Mitsubishi Electric Corporation assumes no responsibility for any damage, liability, or other loss rising from these inaccuracies or errors. Please also pay attention to information published by Mitsubishi Electric Corporation by various means, including the Mitsubishi Semiconductor home page (<http://www.MitsubishiElectric.com>).
- When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to evaluate all information as a total system before making a final decision on the applicability of the information and products. Mitsubishi Electric Corporation assumes no responsibility for any damage, liability or other loss resulting from the information contained herein.
 - Mitsubishi Electric Corporation semiconductors are not designed or manufactured for use in a device or system that is used under circumstances in which human life is potentially at stake. Please contact Mitsubishi Electric Corporation or an authorized Mitsubishi Semiconductor product distributor when considering the use of a product contained herein for any specific purposes, such as apparatus or systems for transportation, vehicular, medical, aerospace, nuclear, or undersea repeater use.
 - The prior written approval of Mitsubishi Electric Corporation is necessary to reprint or reproduce in whole or in part these materials.
 - If these products or technologies are subject to the Japanese export control restrictions, they must be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination.
 - Any diversion or reexport contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited.
 - Please contact Mitsubishi Electric Corporation or an authorized Mitsubishi Semiconductor product distributor for further details on these materials or the products contained therein.



for a greener tomorrow

Eco Changes is the Mitsubishi Electric Group's environmental statement, and expresses the Group's stance on environmental management. Through a wide range of businesses, we are helping contribute to the realization of a sustainable society.



MITSUBISHI ELECTRIC CORPORATION

HEAD OFFICE: TOKYO BLDG., 2-7-3, MARUNOUCHI, CHIYODA-KU, TOKYO 100-8310, JAPAN
www.MitsubishiElectric.com

Revised publication, effective Jul. 2014.
Superseding publication of H-CT575-U Nov. 2013.
Specifications subject to change without notice.

©2014 Mitsubishi Electric Corporation